

L Number	Hits	Search Text	DB	Time stamp
12	1207	((438/595) or (438/596) or (438/599) or (438/598)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 15:53
13	311	((438/595) or (438/596) or (438/599) or (438/598)).CCLS.) and (wire or wires or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:26
14	183	rocchegiani	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:28
15	78	circuit adj layout and wiring and gaps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:38
16	26	("4625227" "4654692" "4797375" "4944836" "4956313" "5023699" "5089442" "5229642" "5234868" "5262354" "5270264" "5272117" "5292689" "5300813" "5362669" "5395790" "5426330" "5471091" "5494854" "5602423" "5621241" "5686356" "6265251" "6342419" "6483150" "6504219").PN.	USPAT	2004/04/01 18:36
17	0	6653717.URPN.	USPAT	2004/04/01 18:37
18	0	6653717.URPN.	USPAT	2004/04/01 18:37
19	7777	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
20	2409	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
21	2530	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire\$1 or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
22	460	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire\$1 or wiring)) and gap\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
23	81	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire\$1 or wiring)) and gap\$1) and (protrusion\$1 or layout)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:32
24	351	(257/210).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:40
25	0	wiring and ((bond adj pad) same contact same photoresist same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:41

26	0	wiring and ((bond adj pad) same hole same photoresist same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:41
27	0	wiring and ((bond adj pad) same hole same photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:41
28	0	wiring and ((bond adj pad) same photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:41
29	0	wiring and ((contact adj pad) same photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:42
30	2	wiring and ((contact adj pad) same photoresist) and (photo same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:43
31	0	wiring and ((contact adj pad) same photo\$5 same mask) and (photo same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:44
32	0	wiring and ((contact adj pad) same photo\$5 same mask) and (photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:44
33	1	wiring and ((contact adj pad) same photo\$5) and (photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:45
34	5	((contact adj pad) same photo\$5) and (photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:45